

## Sound Processor with Built-in 3-band Equalizer BD37531FV

#### **General Description**

BD37531FV is a sound processor with built-in 3-band equalizer for car audio. A stereo input selector is available that functions to switch single end input and ground isolation input, input-gain control, main volume, loudness and 5ch fader volume. Moreover, "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). Also, "Advanced switch" makes microcomputer control easier and constructs a high quality car audio system.

#### Features

- Reduced switching noise of input gain control, mute, main volume, fader volume, bass, middle, treble, loudness by using advanced switch circuit
- Built-in differential input selector that can make various combination of single-ended / differential input.
- Built-in ground isolation amplifier inputs, which is ideal for external stereo input.
- Built-in input gain controller reduces volume switching noise of a portable audio input.
- Decreased number of external components due to built-in 3-band equalizer filter and loudness filter. It is possible to freely control the Q, Gv, fo of the 3-band equalizer, and Gv of the loudness through the I<sup>2</sup>C BUS control
- A gain adjustment quantity of ±20dB with a 1 dB step gain adjustment is possible for the bass, middle and treble.
- Equipped with terminals for the subwoofer outputs. Also, the audio signal outputs of the front, rear and subwoofer can be chosen using the I<sup>2</sup>C BUS control.
- Energy-saving design resulting in low current consumption is achieved utilizing the BiCMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input pins and output pins are organized and separately laid out to keep the signal flow in one direction which consequently, simplify pattern layout of the set board and decrease the board dimensions.
- It is possible to control I<sup>2</sup>C BUS with 3.3V / 5V.

#### Key Specifications

- Power Supply Voltage Range: 7.0V to 9.5V
   Circuit Current (No signal) : 38mA(Typ)
   Total Harmonic Distortion 1:
- (FRONT,REAR) 0.001%(Typ) ■ Total Harmonic Distortion 2: (SUBWOOFER) 0.002%(Typ)
- (SUBWOOFER)0.002%(Typ)Maximum Input voltage:2.3Vrms (Typ)Cross-talk Between Selectors:-100dB (Typ)Volume Control Range:+15dB to -79dBOutput Noise Voltage 1:-100dB (Typ)
- Output Noise Voltage 1: (FRONT,REAR) 3.8µVrms(Typ)
   Output Noise Voltage 2:
- (SUBWOOFER)4.8µVrms(Typ)■ Residual Output Noise Voltage:1.8µVrms(Typ)
- Operating Temperature Range: -40°C to +85°C

#### Package

#### W(Typ) x D(Typ) x H(Max)



#### Applications

It is optimal for car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

**Pin Configuration** 

### **Typical Application Circuit**



### **Pin Descriptions**

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	15	MUTE	External compulsory mute terminal
2	A2	A input terminal of 2ch	16	TEST2	Test Pin
3	B1	B input terminal of 1ch	17	TEST3	Test Pin
4	B2	B input terminal of 2ch	18	OUTS2	Subwoofer output terminal of 2ch
5	C1	C input terminal of 1ch	19	OUTS1	Subwoofer output terminal of 1ch
6	C2	C input terminal of 2ch	20	OUTR2	Rear output terminal of 2ch
7	DP1	D positive input terminal of 1ch	21	OUTR1	Rear output terminal of 1ch
8	DN	D negative input terminal	22	OUTF2	Front output terminal of 2ch
9	DP2	D positive input terminal of 2ch	23	OUTF1	Front output terminal of 1ch
10	EP1	E positive input terminal of 1ch	24	VCC	Power supply terminal
11	EN1	E negative input terminal of 1ch	25	SCL	I <sup>2</sup> C Communication clock terminal
12	EN2	E negative input terminal of 2ch	26	SDA	I <sup>2</sup> C Communication data terminal
13	EP2	E positive input terminal of 2ch	27	GND	GND terminal
14	TEST1	Test Pin	28	FIL	VCC/2 terminal

### **Block Diagram**



### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	Vcc	10.0	V
Input Voltage	Vin	Vcc+0.3 to GND-0.3	V
Power Dissipation	Pd	1.06 <sup>(Note 1)</sup>	W
Storage Temperature	Tstg	-55 to +150	°C

(Note 1) When mounted on ROHM standard board (70 x 70 x 1.6(mm<sup>3</sup>), derate by 8.5mW/°C for Ta above 25°C.

Thermal resistance θja = 117.6(°C/W) Material : A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

### **Recommended Operating Conditions**

Parameter	Symbol	Limit	Unit
Power Supply Voltage	Vcc	7.0 to 9.5	V
Temperature	Topr	-40 to +85	°C

### **Electrical Characteristics**

(Unless otherwise noted, Ta=25°C, V<sub>CC</sub>=8.5V, f=1kHz, V<sub>IN</sub>=1Vrms, Rg=600Ω, R<sub>L</sub>=10kΩ, A1 input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, Fader 0dB)

X				Limit			
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
	Circuit Current	la	-	38	48	mA	No signal
	Voltage Gain	Gv	-1.5	0	+1.5	dB	Gv=20log(Vout/Vin)
	Channel Balance	CB	-1.5	0	+1.5	dB	$CB = G_{V1}-G_{V2}$
	Total Harmonic Distortion 1 (FRONT,REAR)	THD+N1	-	0.001	0.05	%	V <sub>OUT</sub> =1Vrms BW=400Hz-30KHz
	Total Harmonic Distortion 2 (SUBWOOFER)	THD+N2	-	0.002	0.05	%	V <sub>OUT</sub> =1Vrms BW=400HZ-30KHZ
SAL	Output Noise Voltage 1 (FRONT,REAR) *	V <sub>NO1</sub>	-	3.8	15	µVrms	Rg = 0Ω BW = IHF-A
GENERAL	Output Noise Voltage 2 (SUBWOOFER) *	V <sub>NO2</sub>	-	4.8	15	µVrms	Rg = 0Ω BW = IHF-A
Ū	Residual Output Noise Voltage *	V <sub>NOR</sub>	-	1.8	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A
	Crosstalk Between Channels *	СТС	-	-100	-90	dB	Rg = 0Ω CTC=20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V <sub>RR</sub> =100mVrms RR=20log(V <sub>CC</sub> IN/V <sub>OUT</sub> )
	Input Impedance(A, B, C)	RIN_S	70	100	130	kΩ	
	Input Impedance (D, E)	R <sub>IN_D</sub>	175	250	325	kΩ	
TOR	Maximum Input Voltage	Vim	2.1	2.3	-	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1% BW=400Hz-30KHz
INPUT SELECTOR	Crosstalk Between Selectors *	СТЅ	-	-100	-90	dB	$\begin{array}{l} \text{Rg} = 0\Omega \\ \text{CTS} = 20 \text{log}(V_{\text{OUT}}/V_{\text{IN}}) \\ \text{BW} = \text{IHF-A} \end{array}$
INPU <sup>-</sup>	Common Mode Rejection Ratio * (D, E)	CMRR	50	65	-	dB	XP1 and XN input XP2 and XN input CMRR=20log( $V_{IN}/V_{OUT}$ ) BW = IHF-A,[*X···D,E]

### **Electrical Characteristics – continued**

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CK	Deremeter	Ourse al		Limit		د. ۱۰۰۰ د	Conditions
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions
INPUT GAIN	Minimum Input Gain	Gin_min	-2	0	+2	dB	Input gain 0dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )
INPUT	Maximum Input Gain	Gin_max	+18	+20	+22	dB	Input gain +20dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	Gin_err	-2	0	+2	dB	GAIN=+20dB to +1dB
MUTE	Mute Attenuation *	Gmute	-	-105	-85	dB	Mute ON G <sub>MUTE</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
ш	Maximum Gain	G <sub>V_MAX</sub>	13	15	17	dB	Volume = $15dB$ V <sub>IN</sub> =100mVrms Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> )
VOLUME	Maximum Attenuation *	Gv_min	-	-100	-85	dB	Volume = $-\infty dB$ Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
-	Attenuation Set Error 1	GV_ERR1	-2	0	+2	dB	GAIN & ATT=+15dB to -15dB
	Attenuation Set Error 2	Gv_err2	-3	0	+3	dB	ATT=-16dB to -47dB
	Attenuation Set Error 3	Gv_err3	-4	0	+4	dB	ATT=-48dB to -79dB
0	Maximum Boost Gain	G <sub>B_BST</sub>	18	20	22	dB	Gain=+20dB f=100Hz V <sub>IN</sub> =100mVrms GB=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
BASS	Maximum Cut Gain	G <sub>B_CUT</sub>	-22	-20	-18	dB	Gain=-20dB f=100Hz V <sub>IN</sub> =2Vrms GB=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	Gb_err	-2	0	+2	dB	Gain=+20dB to -20dB f=100Hz Gain=+20dB f=1kHz
) ILE	Maximum Boost Gain	<b>G</b> м_вsт	18	20	22	dB	V <sub>IN</sub> =100mVrms G <sub>M</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )
MIDDLE	Maximum Cut Gain	<b>G</b> м_сит	-22	-20	-18	dB	Gain=-20dB f=1kHz V <sub>IN</sub> =2Vrms G <sub>M</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	Gm_err	-2	0	+2	dB	Gain=+20dB to -20dB f=1kHz
щ	Maximum Boost Gain	Gt_bst	18	20	22	dB	Gain=+20dB f=10kHz V <sub>IN</sub> =100mVrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
TREBL	Maximum Cut Gain	<b>G</b> т_сит	-22	-20	-18	dB	Gain=-20dB f=10kHz V <sub>IN</sub> =2Vrms GT=20log (V <sub>OUT</sub> /V <sub>IN</sub> )
	Gain Set Error	Gt_err	-2	0	+2	dB	Gain=+20dB to -20dB f=10kHz
н. К	Maximum Attenuation *	Gf_min	-	-100	-90	dB	Fader = -∞dB GF=20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A
Ц Н	Attenuation Set Error 1	G <sub>F_ERR1</sub>	-2	0	+2	dB	ATT=-1dB to -15dB
Шĕ	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB
FADER / SUBWOOFER	Attenuation Set Error 3	G <sub>F_ERR3</sub>	-4	0	+4	dB	ATT=-48dB to -79dB
Ш	Output Impedance	Rout	-	-	50	Ω	V <sub>IN</sub> =100mVrms
0 0	Maximum Output Voltage	Vom	2	2.2	-	Vrms	THD+N=1% BW=400Hz-30KHz
LOUDNESS	Maximum Gain	Gl_max	17	20	23	dB	Gain 20dB V <sub>IN</sub> =100mVrms GL=20log(V <sub>OUT</sub> /V <sub>IN</sub> )
LOU	Gain Set Error	$G_{L\_ERR}$	-2	0	+2	dB	GAIN=+20dB to +1dB

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for \* measurement. Phase between input / output is same.



Figure 1. Circuit Current (No signal) vs Power Supply Voltage







Figure 3. Gain vs Frequency



Figure 4. Bass Gain vs Frequency













Figure 11. Treble fo vs Frequency



Figure 12. Treble Q vs Frequency



Figure 13. Output Noise vs Volume Gain





Figure 15. Output Noise vs Middle Gain

Figure 16. Output Noise vs Treble Gain



Figure 17. CMRR vs Frequency

Figure 18. Output Voltage vs RLOAD



Figure 19. Advanced Switch 1



Figure 20. Advanced Switch 2

### Timing Chart CONTROL SIGNAL SPECIFICATION

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages



Table 1 Characteristics of the SDA and SCL bus lines for  $l^2$ C-bus devices (Unless specified particularly, Ta=25°C, V<sub>CC</sub>=8.5V)

	Parameter	Symbol	Fast-mode	e l²C-bus	Unit
	Faldineter	Symbol	Min	Max	Unit
1	SCL clock frequency	fscl	0	400	kHz
2	Bus free time between a STOP and START condition	<b>t</b> BUF	1.3	-	μS
3	Hold time (repeated) START condition. After this period, the first clock		0.6		μS
3	pulse is generated	thd;sta	0.6	-	μο
4	LOW period of the SCL clock	tLow	1.3	-	μS
5	HIGH period of the SCL clock	tнigн	0.6	-	μS
6	Set-up time for a repeated START condition	<b>t</b> su;sta	0.6	-	μS
7	Data hold time:	t <sub>HD;DAT</sub>	0.06 (Note)	-	μS
8	Data set-up time	tsu;dat	120	-	ns
9	Set-up time for STOP condition	tsu;sto	0.6	-	μS

### All values referred to VIH Min and VIL Max Levels (see Table 2).

(Note) The device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the VIH Min of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

About 7( $t_{HD;DAT}$ ), 8( $t_{SU;DAT}$ ), make the setup in which the margin is fully in .

### Table 2 Characteristics of the SDA and SCL I/O stages for I<sup>2</sup>C-bus devices

	Parameter	Sumbol	Fast-mode	Unit	
	Parameter	Symbol	Min	Max	Unit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	Vih	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	tsp	0	50	ns
13	LOW level output voltage: at 3mA sink current	V <sub>OL1</sub>	0	0.4	V
14	Input current each I/O pin with an input voltage between 0.4V and 4.5V.	lı	-10	+10	μA





### (2) <u>I<sup>2</sup>C BUS FORMAT</u>

Μ	MSB LSB		MSB I	SB	MSB	LSB						
S	Slave Address	Α	Select Address	А	Dat	а	А	Р				
1bit	8bit	1bit	8bit	1bit	8b	it	1bit	1bit				
	S = Start conditions (Recognition of start bit)											
	Slave Address	Slave Address = Recognition of slave address. 7 bits in upper order are voluntary.										
		Th	e least significant b	it is "L" du	ue to writing.							
	A		KNOWLEDGE bit (			ledgement)						
	Select Address	= Se	lect every of volum	e, bass ai	nd treble.							
	Data	Data = Data on every volume and tone.										
	Р	= Sto	op condition (Recog	nition of s	stop bit)							

### (3) <u>I<sup>2</sup>C BUS Interface Protocol</u>

(u) i													
S	Slave Addre	ess A	Ą	Select Addres	А	Data		Α	Р				
	MSB	LSB		MSB	LSB	N	1SB	LS	BB		-		

S	Sla	ve Address	А	Select Address		А	Da	ta1	А	A Data2		 Data	DataN		Ρ
	MSB	LSE	3	MSB	LSB		MSB	LSB	Ν	ISB LS	βB	MSB	Ľ	SB	
(Exar	(Example) ①Data1 shall be set as data of address specified by Select Address.														
		2 Data2 sha	ll be	set as da	ta of addre	ess s	specifie	ed by S	Seleo	ct Address +	-1.				
		③DataN sha	ıll be	e set as da	ata of addr	ess	specifi	ed by	Sele	ct Address ·	+N-1.				

(c) Configuration Unavailable for Transmission (In this case, only Select Address1 is set.

S	5 5	Slave Address	Α	Select Addre	ess1	А	Da	ata	Α	Select A	Address 2	Α	Dat	ta	Α	Ρ
	MSB LSB MSB LSB MSB LSB MSB LSB MSB									LS	В					
	(Note) If any data is transmitted as Select Address 2 next to data, it is recognized															
	as data, not as Select Address 2.															

### (4) Slave Address

I	MSB							LSB	
	A6	A5	A4	A3	A2	A1	A0	R/W	
	1	0	0	0	0	0	0	0	80H

(5) <u>Select Address & Data</u>

Items	Select Address	MSB			Da	ata			LSB		
nems	(hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advanced switch ON/OFF	0	of Input G	switch time ain/Volume r/Loudness	0	1		switch time /lute		
Initial setup 2	02	0	0		er Output lect	0	0	0	0		
Initial setup 3	03	0	0	0	Loudn	ess fo	0	0	1		
Input Selector	05	Full-diff Type	0	0		Ir	nput selecto	or			
Input gain	06	Mute ON/OFF	0	0			Input Gain				
Volume gain	20			١	/olume Gain	/ Attenuation	า				
Fader 1ch Front	28				Fader At	ttenuation					
Fader 2ch Front	29				Fader Attenuation						
Fader 1ch Rear	2A				Fader At	ttenuation					
Fader 2ch Rear	2B				Fader Attenuation						
Fader Subwoofer	2C				Fader At	ttenuation					
Test Mode	30	1	1	1	1	1	1	1	1		
Bass setup	41	0	0	Bas	ss fo	0	0	Bas	ss Q		
Middle setup	44	0	0	Mide	dle fo	0	0	Mide	dle Q		
Treble setup	47	0	0	Treb	ole fo	0	0	0	Treble Q		
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gain				
Middle gain	54	Middle Boost/ Cut	0	0	Middle Gain						
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain						
Loudness Gain	75	0	Loudne	ess Hicut	cut Loudness Gain						
System Reset	FE	1	0	0	0	0	0	0	1		

Advanced switch

### Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.



- 3. Advanced switch is not used for functions of input selector and subwoofer output select etc. Therefore, please turn on MUTE when changing the settings of this side of a set.
- 4. When using Mute function of this IC at the time of changing input selector, please switch mute ON/OFF while waiting for advanced-mute time.

### Select address 01 (hex)

Time	MSB	Ac	dvance	ed swit	ch tim	e of M	ute	LSB
Time	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	Advanaad		Advonced	owitch time			0	0
1.0msec	Advanced Switch	0	Advanced switch tim of Input gain/Volume		0	1	0	1
1.4msec	ON/OFF	0		r/Loudness	0	I.	1	0
3.2msec			Tone/Faue	Louuness			1	1

Time	MSB	Advanced switch time of Input gain/Volume/Tone/Fader/Loudness									
	D7	D6	D5	D4	D3	D2	D1	D0			
4.7 msec	Advanced Switch ON/OFF		0	0							
7.1 msec		0	0	1	0	1	Advance	ed switch			
11.2 msec			1	0	0	I	Time of Mute				
14.4 msec			1	1							

Mode	MSB		Advan	ced sv	vitch C	vitch ON/OFF					
Mode	D7	D6	D5	D4	D3	D2	D1	D0			
OFF	0	0		Advanced switch time of Input gain/Volume		1	Advanced switch Time of Mute				
ON	1		Tone/Fader/Loudness								

### Select address 02(hex)

Mode	MSB		Subw	oofer (	Dutput	Selec	t	LSB
Widde	D7	D6	D5	D4	D3	D2	D1	D0
Sub			0	0				
Front	0		0	1	0	0		0
Rear	0	0	1	0	0	0	0	0
Prohibition			1	1				

### Select address 03(hex)

f0	MSB			Loudr	ess fo			LSB
ťŬ	D7	D6	D5	D4	D3	D2	D1	D0
250Hz				0	0			
400Hz	_	0	0	0	1	0	0	1
800Hz	0	0	0	1	0	0	0	1
Prohibition				1	1			

: Initial Condition

### Select address 05(hex)

Mada			MSB			Input S	elector			LSB
Mode	OUTF1	OUTF2	D7	D6	D5	D4	D3	D2	D1	D0
А	A1	A2				0	0	0	0	0
В	B1	B2				0	0	0	0	1
С	C1	C2				0	0	0	1	0
D single	DP1	DP2				0	0	0	1	1
E1 single	EP1	EN1	Full-diff			0	1	0	1	0
E2 single	EN2	EP2	bias	0	0	0	1	0	1	1
A diff	A1	B1	type	0	0	0	1	1	1	1
C diff	B2	C2	select			1	0	0	0	0
D diff	DP1	DP2				0	0	1	1	0
E full diff	EP1	EP2				0	1	0	0	0
Inp	ut SHORT					0	1	0	0	1
	rohibition							Other setting		

Input SHORT : The input impedance of each input terminal is lowered from  $100k\Omega(Typ)$  to  $6 k\Omega(Typ)$ . (For quick charge of coupling capacitor)

Mode	MSB	MSB Full-diff Bias Type Select LS										
Mode	D7	D6	D5	D4	D3	D2	D1	D0				
Negative Input	0	0	0		r							
Bias	1	U	0	Input Selector								



Gain	MSB			Input	Gain			LS
Gain	D7	D6	D5	D4	D3	D2	D1	D
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	(
7dB				0	0	1	1	1
8dB				0	1	0	0	(
9dB				0	1	0	0	1
10dB				0	1	0	1	(
11dB	Mute	0	0	0	1	0	1	1
12dB	ON/OFF	0	0	0	1	1	0	(
13dB				0	1	1	0	1
14dB				0	1	1	1	(
15dB				0	1	1	1	1
16dB				1	0	0	0	(
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	1	0	1	1
Prohibition				:	:	:	:	
				1	1	1	1	1

Mode	MSB				LSB			
Wode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	0			Input Gain		
ON	1	0	0			Input Gain		

: Initial condition

Select address 20, 28, 29	9, 2A, 2B, 2C	(hex)						
Gain & ATT	MSB		ol, Fad	er Gai	n / Atte	enuatio	on	LSB
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0
	0	0	0	0	0	0	0	0
	0	0	0	0	0	0	0	1
Prohibition	:	:	:	:	:	:	:	:
	0	1	1	1	0	0	0	0
15dB	0	1	1	1	0	0	0	1
14dB	0	1	1	1	0	0	1	0
13dB	0	1	1	1	0	0	1	1
:	:	:	:	:	:	:	:	:
-77dB	1	1	0	0	1	1	0	1
-78dB	1	1	0	0	1	1	1	0
-79dB	1	1	0	0	1	1	1	1
	1	1	0	1	0	0	0	0
Prohibition	:	:	:	:	:	•	:	:
	1	1	1	1	1	1	1	0
-∞dB	1	1	1	1	1	1	1	1

(Only 0dB to -∞dB are available at address 28, 29, 2A, 2B, 2C)

### Select address 41(hex)

Q factor	MSB		Bass Q			l factor		
Q laciol	D7	D6	D5	D4	D3	D2	D1	D0
0.5							0	0
1.0	0	0	Baa	a fa	0	0	0	1
1.5	0	0	Das	ss fo	0	0	1	0
2.0							1	1

fo	MSB			Bass	fo			LSB
fo	D7	D6	D5	D4	D3	D2	D1	D0
60Hz			0	0				
80Hz	0	0	0	1	0	0	Ba	ass actor
100Hz	0	0	1	0	0	0	Q fa	actor
120Hz			1	1				

### Select address 44(hex)

Q factor	MSB		Middle			Q factor		
QIACIOI	D7	D6	D5	D4	D3	D2	D1	D0
0.75							0	0
1.0	0	0	Mid	dle fo	0	0	0	1
1.25	0	0	IVIICO		0	0	1	0
1.5							1	1

fo	MSB			Middle	fo		L	SB
to	D7	D6	D5	D4	D3	D2	D1	D0
500Hz			0	0				
1kHz	0	0	0	1	0	0		ldle
1.5kHz	0	0	1	0	0	0	Q fa	actor
2.5kHz			1	1				

### Select address 47 (hex)

Q factor	MSB		Tre	əble	Q facto	or		LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0.75	0	0	Trok	ole fo	0	0	0	0
1.25	0	0	neu		0	0	0	1

fo	MSB			Treble	e fo			LSB
fo	D7	D6	D5	D4	D3	D2	D1	D0
7.5kHz			0	0				
10kHz	0	0	0	1	0	0	0	Treble
12.5kHz	0	0	1	0	0	0	0	Q factor
15kHz			1	1				

: Initial condition

Gain	MSB	E	3ass/№	/iddle/	Treble	Gain		LSE
Gain	D7	D6	D5	D4	D3	D2	D1	D
0dB				0	0	0	0	(
1dB				0	0	0	0	1
2dB				0	0	0	1	(
3dB				0	0	0	1	-
4dB				0	0	1	0	(
5dB				0	0	1	0	-
6dB				0	0	1	1	(
7dB				0	0	1	1	1
8dB				0	1	0	0	(
9dB				0	1	0	0	-
10dB	Bass/			0	1	0	1	(
11dB	Middle/			0	1	0	1	-
12dB	Treble	0	0	0	1	1	0	(
13dB	Boost		_	0	1	1	0	-
14dB	/cut			0	1	1	1	(
15dB				0	1	1	1	-
16dB				1	0	0	0	(
17dB				1	0	0	0	-
18dB				1	0	0	1	(
19dB				1	0	0	1	-
20dB				1	0	1	0	(
				1	0	1	0	-
Prohibition				:	:	:	:	
				1	1	1	1	(
				1	1	1	1	1

Mode	MSB	Bas	ss/Mid	dle/Tre	eble Bo	oost/C	ut	LSB
wode	D7	D6	D5	D4	D3	D2	D1	D0
Boost	0	0	0		Base/	Middle/Treble	Gain	
Cut	1	0	0		Da55/1		Gairi	

Γ

: Initial condition

#### Select address 75 (hex) MSB LSB Loudness Hicut Mode D5 D7 D6 D4 D3 D2 D1 D0 Hicut1 0 0 Hicut2 0 1 0 Loudness Gain Hicut3 1 0 Hicut4 1 1

Gain	MSB		L	oudne	ess Ga	in		LSB
Gain	D7	D6	D5	D4	D3	D2	D1	D0
0dB			•	0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB				0	1	0	1	1
12dB	0	Loudne	ss Hicut	0	1	1	0	0
13dB				0	1	1	0	1
14dB				0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	•••	:	:
				1	1	1	1	1

: Initial condition

### (6) About Power ON Reset

Built-in IC initialization is made during power ON of the supply voltage. Please send initial data to all addresses at supply voltage on. Also, please turn ON MUTE at the set side until initial data is sent.

Doromotor	Symbol		Limit		Unit	Conditions
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Rise Time of VCC	t <sub>RISE</sub>	33	-	-	µsec	$V_{\text{CC}}$ rise time from 0V to 5V
VCC Voltage of Release Power ON Reset	V <sub>POR</sub>	-	4.1	-	V	

### (7) About External Compulsory Mute Terminal

It is possible to forcibly set Mute from the outside by setting input voltage at the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

### **Application Information**

### 1. Function and Specifications

Function	Specifications								
	· (Stereo input)								
	Single-End/Diff/Full-Diff								
	(Possible to set the number of single-end/diff/full-diff as follows )								
land	Mode 1	Single-End 0	Differential 3	Full-Differential					
Input selector	Mode 1 Mode 2	1	2	1					
	Mode 3	3	1	1					
	Mode 4 Mode 5	<u>4</u> 5	0	<u> </u>					
	Mode 6	6	0	0					
		Table.3 C	ombination of inp	out selector					
Input	• +20dB to	0dB (1dB step)	)						
gain	<ul> <li>Possible t</li> </ul>	o use "Advanc	ed switch" for pre	evention of switching	noise.				
Mute	<ul> <li>Possible t</li> </ul>	o use "Advanc	ed switch" for pre	evention of switching	noise.				
	• +15dB to -79dB (1dB step), -∞dB								
Volume	Possible to use "Advanced switch" for prevention of switching noise.								
	• +20dB to -20dB (1dB step)								
	· Q=0.5, 1, 1.5, 2								
Bass	• fo=60, 80, 100, 120Hz								
	Possible to use "Advanced switch" when changing gain								
	• +20dB to -20dB (1dB step)								
	· Q=0.75, 1, 1.25, 1.5								
Middle	• fo=500, 1k, 1.5k 2.5kHz								
	Possible to use "Advanced switch" when changing gain								
	<ul> <li>+20dB to -20dB (1dB step)</li> </ul>								
	• Q=0.75, 1.25								
Treble	• fo=7.5k, 10k, 12.5k, 15kHz								
	Possible to use "Advanced switch" when changing gain								
	• 0dB to -79								
Fader	<ul> <li>Possible to use "Advanced switch" for prevention of switching noise.</li> </ul>								
		20dB to 0dB(1dB step)							
Loudness		• fo=250/400/800Hz							
	Possible to use "Advanced switch" for prevention of switching noise.								

### 2. Volume / Fader volume attenuation of the details

2. Volume	e / Fac	der vo	olume	atten	uatio	n of t	he de	etails									
(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
+15	0	1	1	1	0	0	0	1	-33	1	0	1	0	0	0	0	1
+14	0	1	1	1	0	0	1	0	-34	1	0	1	0	0	0	1	0
+13	0	1	1	1	0	0	1	1	-35	1	0	1	0	0	0	1	1
+12	0	1	1	1	0	1	0	0	-36	1	0	1	0	0	1	0	0
+11	0	1	1	1	0	1	0	1	-37	1	0	1	0	0	1	0	1
+10	0	1	1	1	0	1	1	0	-38	1	0	1	0	0	1	1	0
+9	0	1	1	1	0	1	1	1	-39	1	0	1	0	0	1	1	1
+8	0	1	1	1	1	0	0	0	-40	1	0	1	0	1	0	0	0
+7	0	1	1	1	1	0	0	1	-41	1	0	1	0	1	0	0	1
+6	0	1	1	1	1	0	1	0	-42	1	0	1	0	1	0	1	0
+5	0	1	1	1	1	0	1	1	-43	1	0	1	0	1	0	1	1
+4	0	1	1	1	1	1	0	0	-44	1	0	1	0	1	1	0	0
+3	0	1	1	1	1	1	0	1	-45	1	0	1	0	1	1	0	1
+2	0	1	1	1	1	1	1	0	-46	1	0	1	0	1	1	1	0
+1	0	1	1	1	1	1	1	1	-47	1	0	1	0	1	1	1	1
0	1	0	0	0	0	0	0	0	-48	1	0	1	1	0	0	0	0
-1	1	0	0	0	0	0	0	1	-49	1	0	1	1	0	0	0	1
-2	1	0	0	0	0	0	1	0	-50	1	0	1	1	0	0	1	0
-3	1	0	0	0	0	0	1	1	-51	1	0	1	1	0	0	1	1
-4	1	0	0	0	0	1	0	0	-52	1	0	1	1	0	1	0	0
-5	1	0	0	0	0	1	0	1	-53 -54	1	0	1	1	0	1	0	1
-6 -7	1 1	0	0	0	0	1	1	0	-54 -55	1	0	1	1	0	1	1	0
-7	1	0	0	0	1	0	0	0	-55	1	0	1	1	1	0	0	0
-0	1	0	0	0	1	0	0	1	-57	1	0	1	1	1	0	0	1
-10	1	0	0	0	1	0	1	0	-58	1	0	1	1	1	0	1	0
-11	1	0	0	0	1	0	1	1	-59	1	0	1	1	1	0	1	1
-12	1	0	0	0	1	1	0	0	-60	1	0	1	1	1	1	0	0
-13	1	0	0	0	1	1	0	1	-61	1	0	1	1	1	1	0	1
-14	1	0	0	0	1	1	1	0	-62	1	0	1	1	1	1	1	0
-15	1	0	0	0	1	1	1	1	-63	1	0	1	1	1	1	1	1
-16	1	0	0	1	0	0	0	0	-64	1	1	0	0	0	0	0	0
-17	1	0	0	1	0	0	0	1	-65	1	1	0	0	0	0	0	1
-18	1	0	0	1	0	0	1	0	-66	1	1	0	0	0	0	1	0
-19	1	0	0	1	0	0	1	1	-67	1	1	0	0	0	0	1	1
-20	1	0	0	1	0	1	0	0	-68	1	1	0	0	0	1	0	0
-21	1	0	0	1	0	1	0	1	-69	1	1	0	0	0	1	0	1
-22	1	0	0	1	0	1	1	0	-70	1	1	0	0	0	1	1	0
-23	1	0	0	1	0	1	1	1	-71	1	1	0	0	0	1	1	1
-24	1	0	0	1	1	0	0	0	-72	1	1	0	0	1	0	0	0
-25	1	0	0	1	1	0	0	1	-73	1	1	0	0	1	0	0	1
-26	1	0	0	1	1	0	1	0	-74	1	1	0	0	1	0	1	0
-27	1	0	0	1	1	0	1	1	-75	1	1	0	0	1	0	1	1
-28	1	0	0	1	1	1	0	0	-76	1	1	0	0	1	1	0	0
-29	1	0	0	1	1	1	0	1	-77	1	1	0	0	1	1	0	1
-30	1	0	0	1	1	1	1	0	-78	1	1	0	0	1	1	1	0
-31	1	0	0	1	1	1	1	1	-79	1	1	0	0	1	1	1	1
-32 Fader Volun	1	0	1	0	0	0	0	0	-∞	1	1	1	1	1	1	1	1

Fader Volume only 0dB to -∞dB are available.

: Initial condition

### 3. Application Circuit



#### Notes on wiring

- ① Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- GND lines should be one-point connected.
- ③ Wiring pattern of Digital shall be away from that of analog unit and crosstalk should not be acceptable.
- 4 If possible, SCL and SDA lines of the I<sup>2</sup>C BUS should not be parallel.
- The lines should be shielded, if they are adjacent to each other.
- (5) If possible, analog input lines should not be parallel. The lines should be shielded, if they are adjacent to each other.
- 6 About TEST pin(14,16,17pin), should be OPEN.

### **Power Dissipation**

About the thermal design of the IC

Characteristics of an IC are greatly affected by the temperature at which it is used. Exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.



Figure 23. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

### I/O Equivalent Circuits

- <u></u>								
Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description				
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25	VCC VCC VCC VOC VOC VOC VOC VOC	A terminal for signal input. The input impedance is 100kΩ (Typ).				
7 8 9 10 11 12 13	DP1 DN DP2 EP1 EN1 EN2 EP2	4.25		Input terminal available to single/Differential mode. The input impedance is 250kΩ (Typ).				
15	MUTE	-		A terminal for external compulsory mute. If terminal voltage is High level, the mute is OFF. And if the terminal voltage is Low level, the mute is ON.				
18 19 20 21 22 23	OUTS2 OUTS1 OUTR2 OUTR1 OUTF2 OUTF1	4.25		A terminal for fader and Subwoofer output.				

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

### I/O Equivalent Circuits – continued

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
24	VCC	8.5		Power supply terminal.
25	SCL	-	VCC	A terminal for clock input of I <sup>2</sup> C BUS communication.
26	SDA	-	VCC GND GND GND GND GND GND GND GND GND GND	A terminal for data input of I <sup>2</sup> C BUS communication.
27	GND	0		Ground terminal.
28	FIL	4.25		Voltage for reference bias of analog signal system. The simple pre-charge circuit and simple discharge circuit for an external capacitor are built in.
14 16 17	TEST	-		TEST terminal

Values in the pin explanation and input/output equivalent circuit are for reference purposes only. It is not a guaranteed value.

### **Operational Notes**

### 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

### 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

### 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

### 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

### 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

### 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

### 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

### 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

### 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

### 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

### 11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

### **Operational Notes – continued**

#### 12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



Figure 24. Example of monolithic IC structure

#### 13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value The constant value of input coupling capacitor C(F) is decided with respect to the input impedance R<sub>IN</sub>(Ω) at the input signal terminal of the IC that would be sufficient to form an RC characterized HPF.



(b) About the Input Selector SHORT

SHORT mode is the command which makes switch  $S_{SH}$  =ON of input selector part so that the input impedance  $R_{IN}$  of all terminals becomes small. Switch  $S_{SH}$  is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of  $S_{SH}$  and makes it low impedance, please use it at no signal condition.

#### 14. About Mute Terminal (Pin 15) when Power Supply is OFF

There should be no applied voltage to Mute terminal (Pin 15) when power-supply is OFF. If in case voltage is supplied to Mute terminal, please insert a series resistor (about  $2.2k\Omega$ ) to Mute terminal. (Please refer to Application Circuit Diagram.)

#### 15. About TEST Pin

TEST Pin should be OPEN. Pin 14. 16, 17 are TEST Pins

### **Ordering Information**



### **Marking Diagram**



### **Physical Dimension, Tape and Reel Information**



### **Revision History**

Date	Revision	Changes
16.Dec.2015	001	New Release

# Notice

### Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

#### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

#### **Precaution Regarding Intellectual Property Rights**

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#### **Other Precaution**

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- 4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

### **General Precaution**

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in an y way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
- 2. All information contained in this docume nt is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sale s representative.
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